



# Catálogo

SM-6700



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- Suitable for the cleaning of flux residues before molding of high-capacity PBGA, Flip-Chip, SIP, Lead Frame, IC substrate and other packaged devices
- Complete chemical cleaning, pure water rinsing and drying in-line. Meet the cleaning requirements of large size and small bottom gap
- Excellent cleaning effect, effectively remove flux, organic and inorganic contaminants
- Wind cutting + hot air circulation, fast drying; optional spray cleaning knife for better cleaning effect
- Provide automation solutions for loading/unloading
- The overall stainless steel body meets the cleaning needs of high temperature chemicals
- The arrangement of the spray rods can be matched with future upgrades and process requirements to facilitate more complex cleaning
- Customizable multi-channel transmission system
- The machine is equipped with indoor lighting to improve the recognition of the process area